



EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100% die transfer yield on multi-die 3D SoC – August 3, 2022



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EV Group achieves die-to-wafer fusion and hybrid bonding milestone with 100% die transfer yield on multi-die 3D SoC

EV Group (EVG) announced it has achieved a major breakthrough in die-to-wafer (D2W) fusion and hybrid bonding by successfully demonstrating 100-percent void-free bonding yield of multiple die of different sizes from a complete 3D system-on-a-chip (SoC) in a single transfer process using EVG's GEMINI FB automated hybrid bonding system. [More>>](#)

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